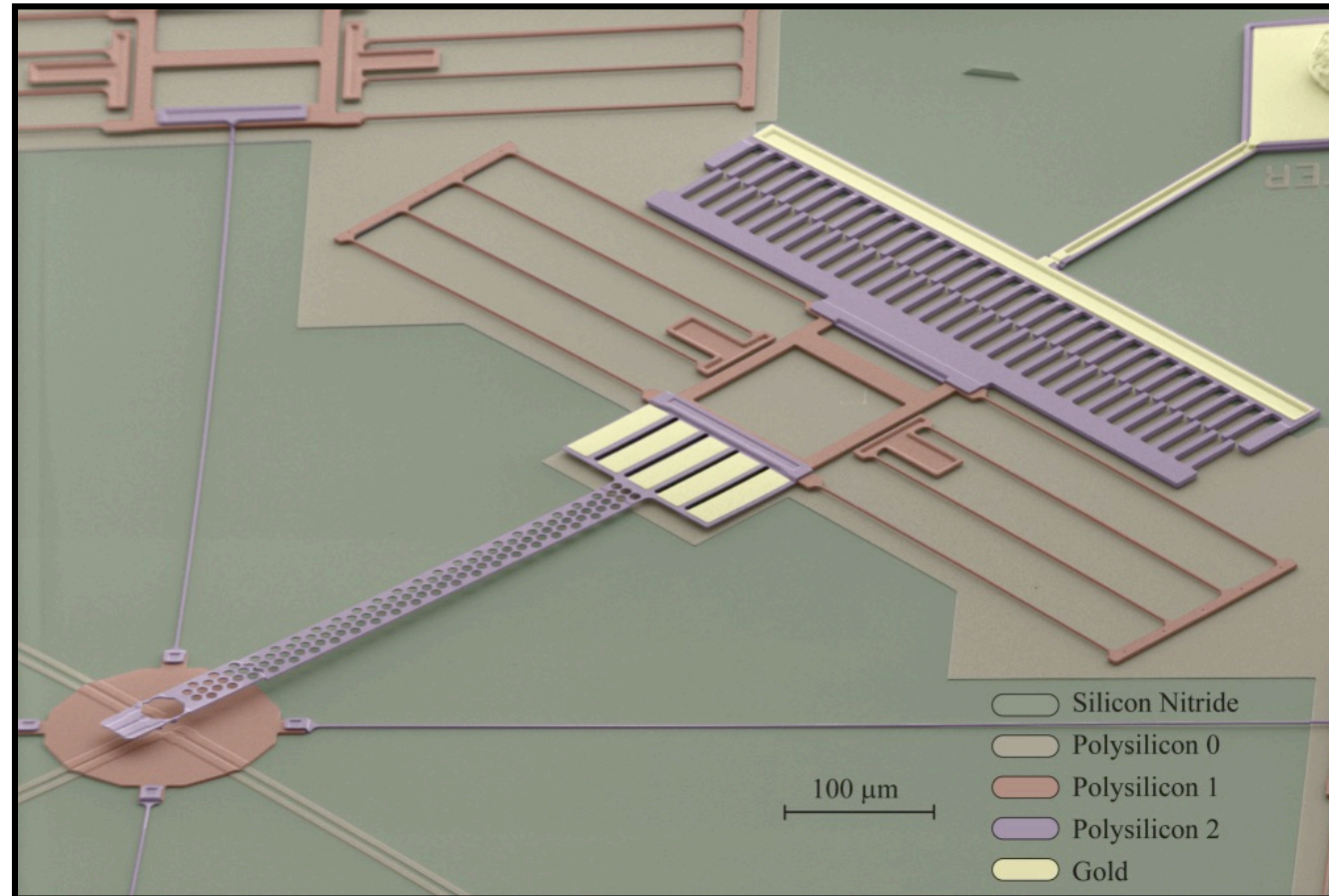


Fab-on-a-Chip: A Micron Scale Workshop for Nano Fabrication



David Bishop, Ph.D.

Director, CELL-MET NSF ERC

Head, Division of Materials Science and Engineering

Professor of Physics

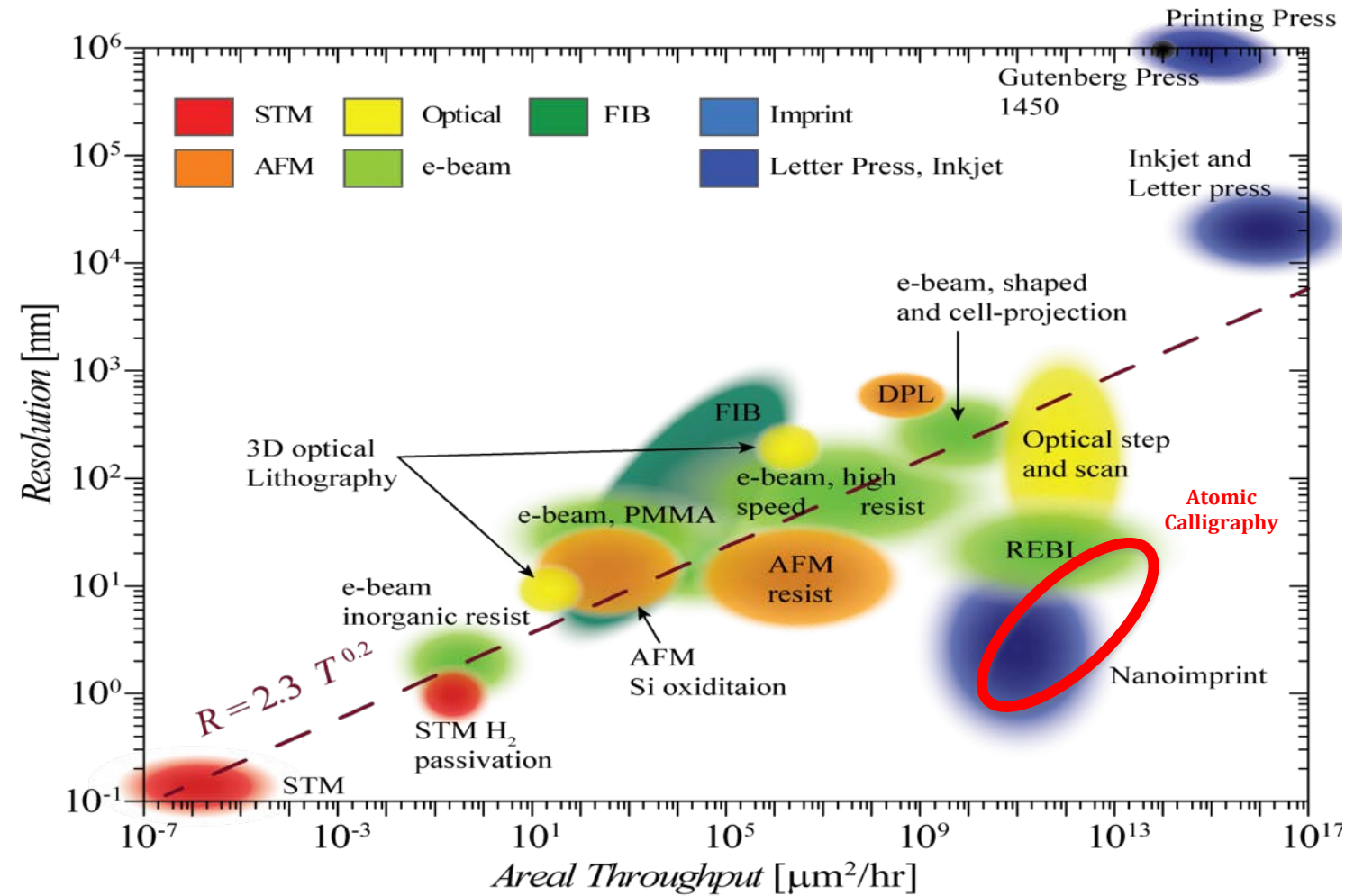
Professor of Electrical and Computer Engineering

Professor of Materials Science and Engineering

Professor of Mechanical Engineering

Professor of Biomedical Engineering

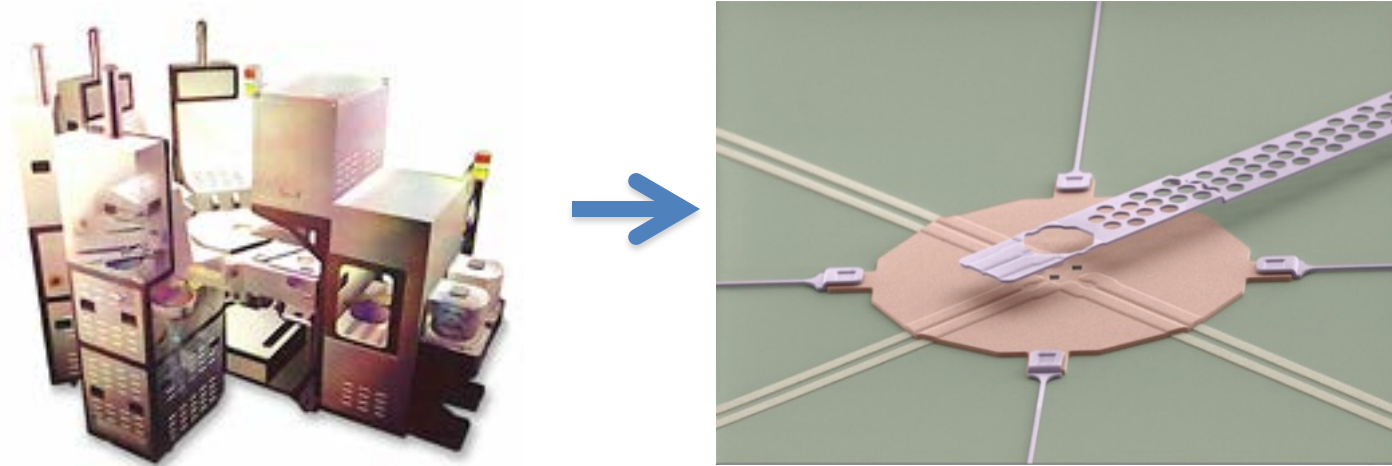
From Nano-Fabrication to Nanomanufacturing



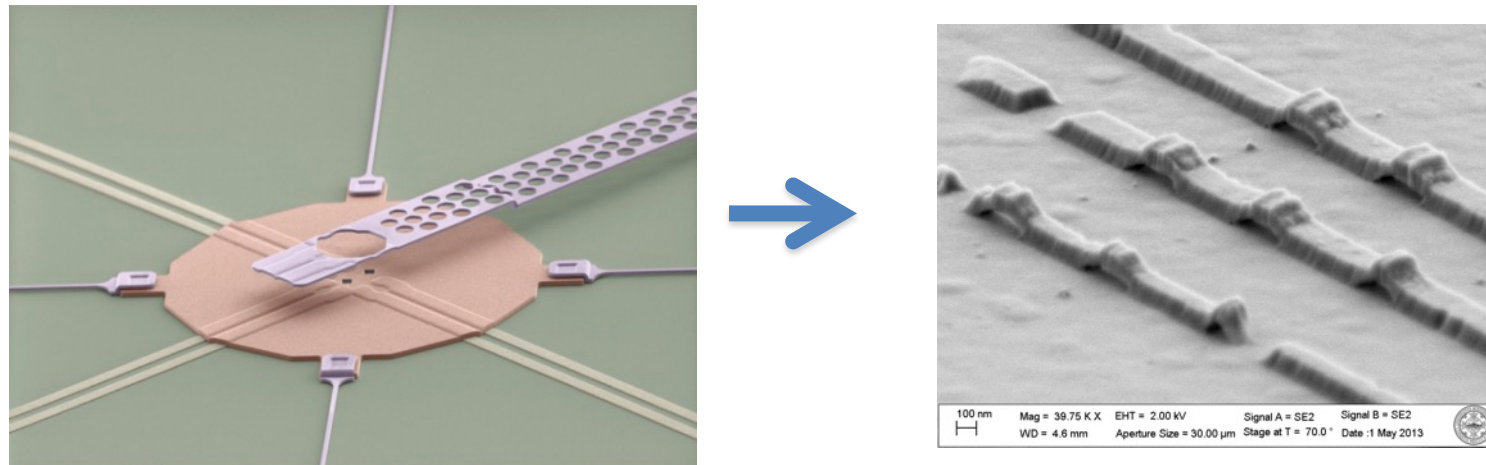
Tennant's law: Improving resolution results in a large penalty on throughput

Basic Approach

Use Macro Machines to build Micro Machines

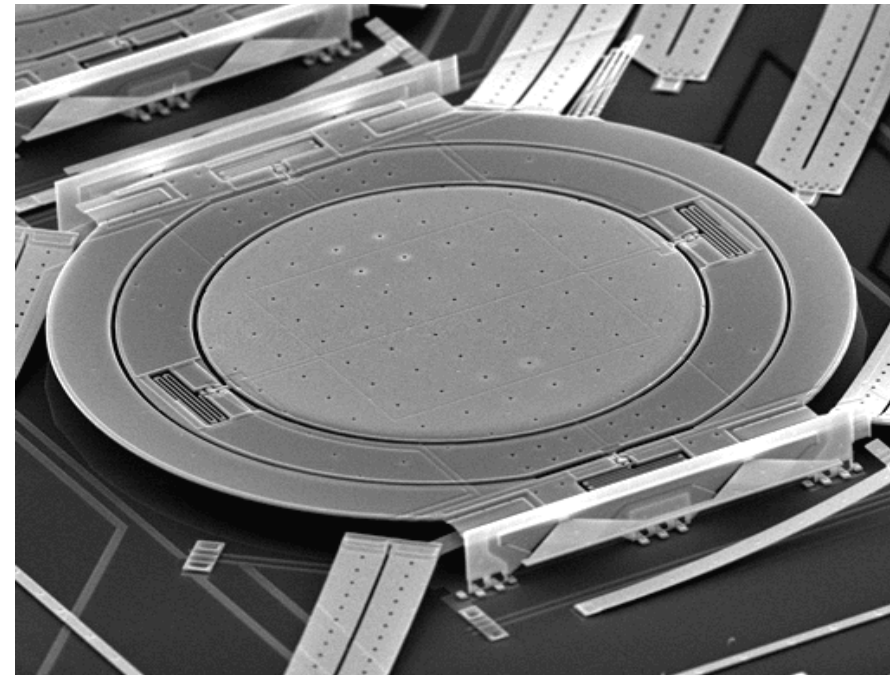


Then use Micro Machines to build Nano Machines



Micro-Electromechanical Systems (MEMS)

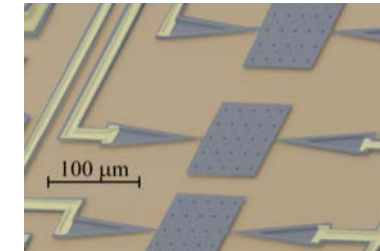
- MEMS are micro-machines that use mechanical degrees of freedom to sense and actuate on the micron scale
- The approach to fabrication uses, as a basis, the materials and processes of microelectronics (IC)
- The main difference with an IC process is the release step, at which sacrificial materials are removed, allowing the structural materials to be free to move
- Coupling to the mechanical degree of freedom is typically capacitive, piezoelectric, thermoelectric or optical



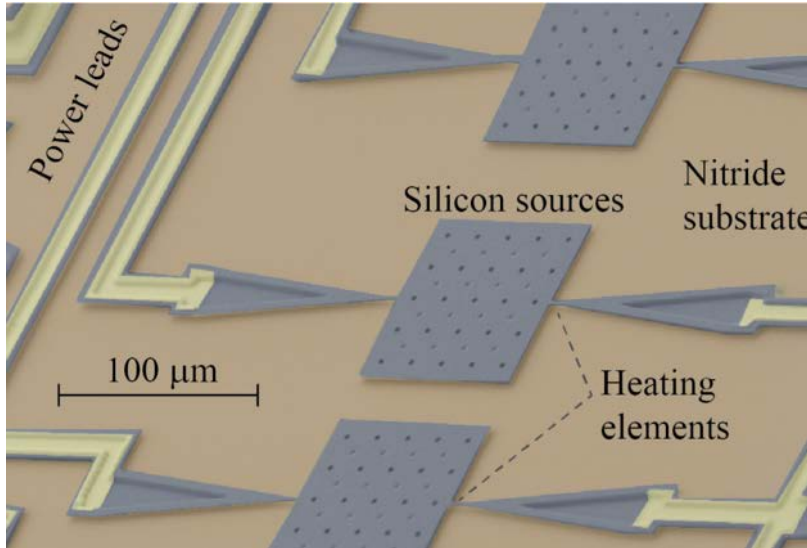
Actuators

-
- 20 μm Mag = 50k X EHT = 2.00 kV Signal A = SE2 Signal B = SE2
WD = 5.8 mm Aperture Size = 30.00 μm Stage at T = 0.0" Date: 7 Mar 2013

-



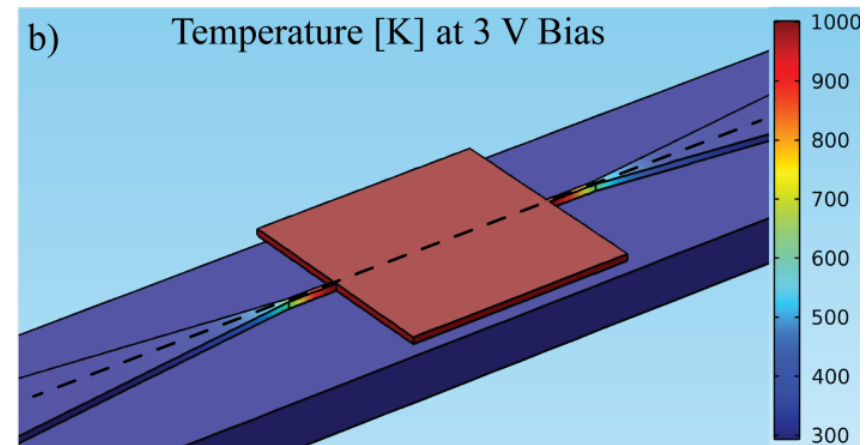
5

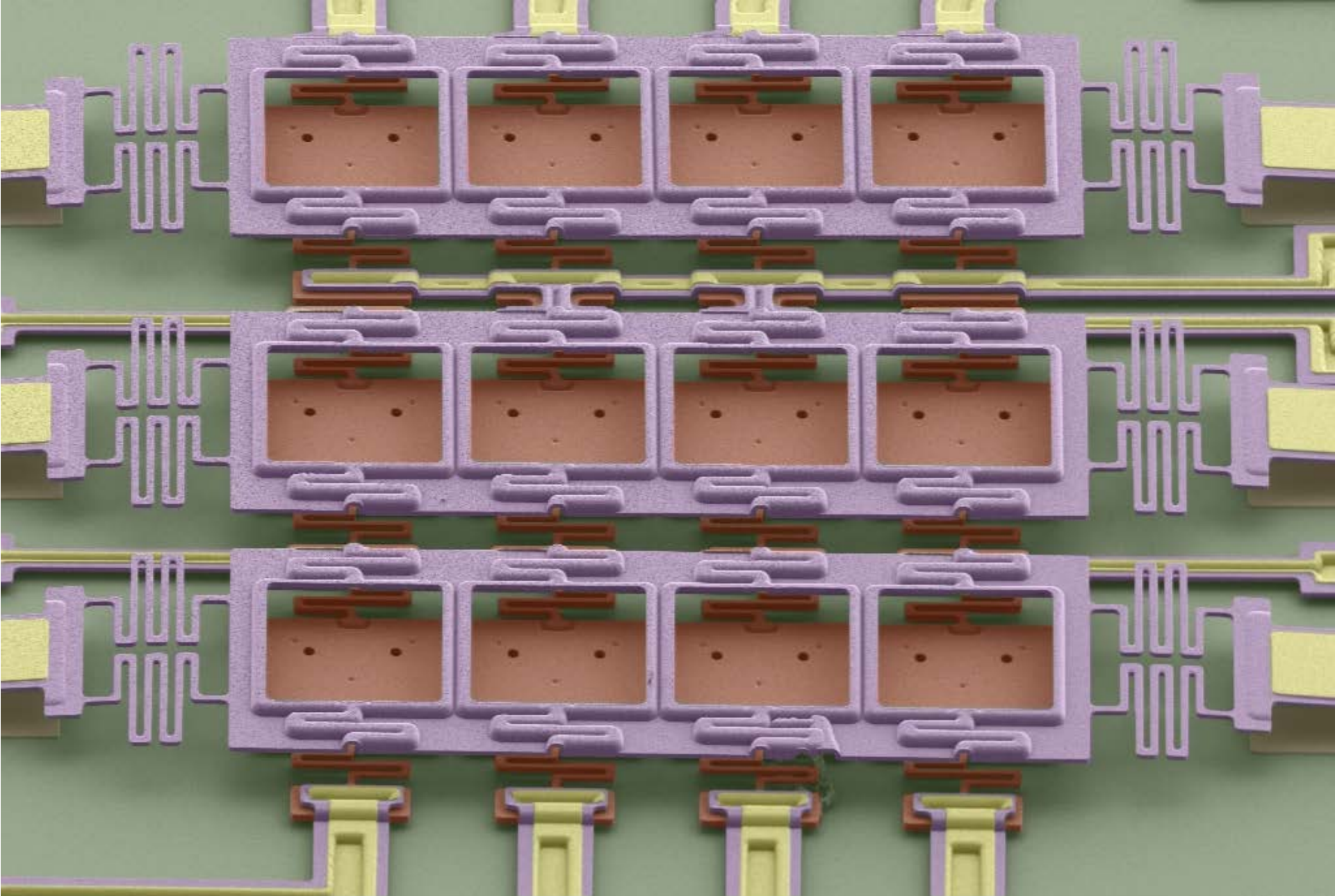


- Suspended Silicon plates ranging from $50 \times 50 \mu\text{m}^2$ to $150 \times 150 \mu\text{m}^2$
- Constrictions result in heating elements
- Al_2O_3 can electrically isolate and protect the poly-silicon
- Loaded using shadow masks with the desired material

Finite Element Simulation:

- At 1000 K the plate temperature is uniform to within 4 K
- up to $\sim 30 \text{ mW}$ before silicon melts (1683 K)





20 μm

Mag = 329 X
WD = 4.6 mm

EHT = 2.00 kV

Aperture Size = 30.00 μm

Signal A = SE2

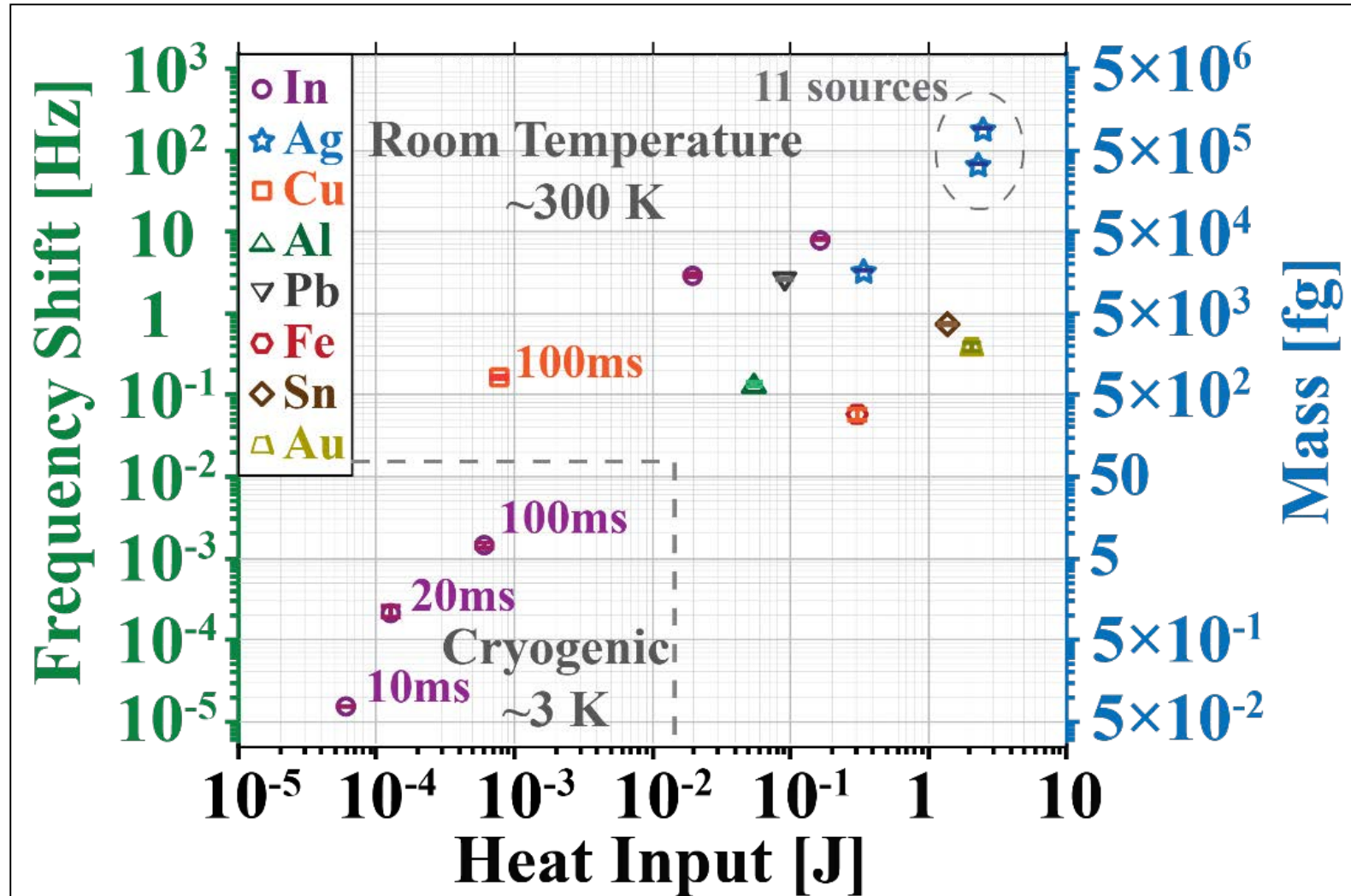
Stage at T = 50.0 °

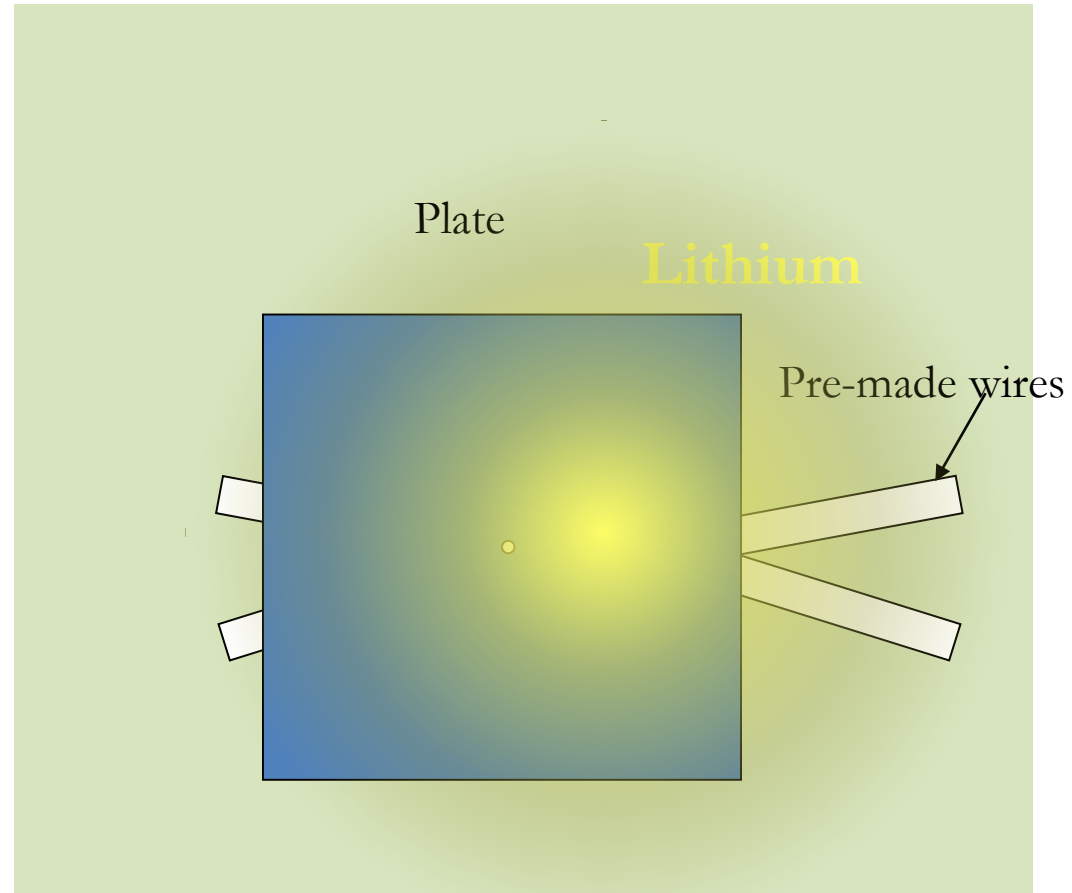
Signal B = SE2

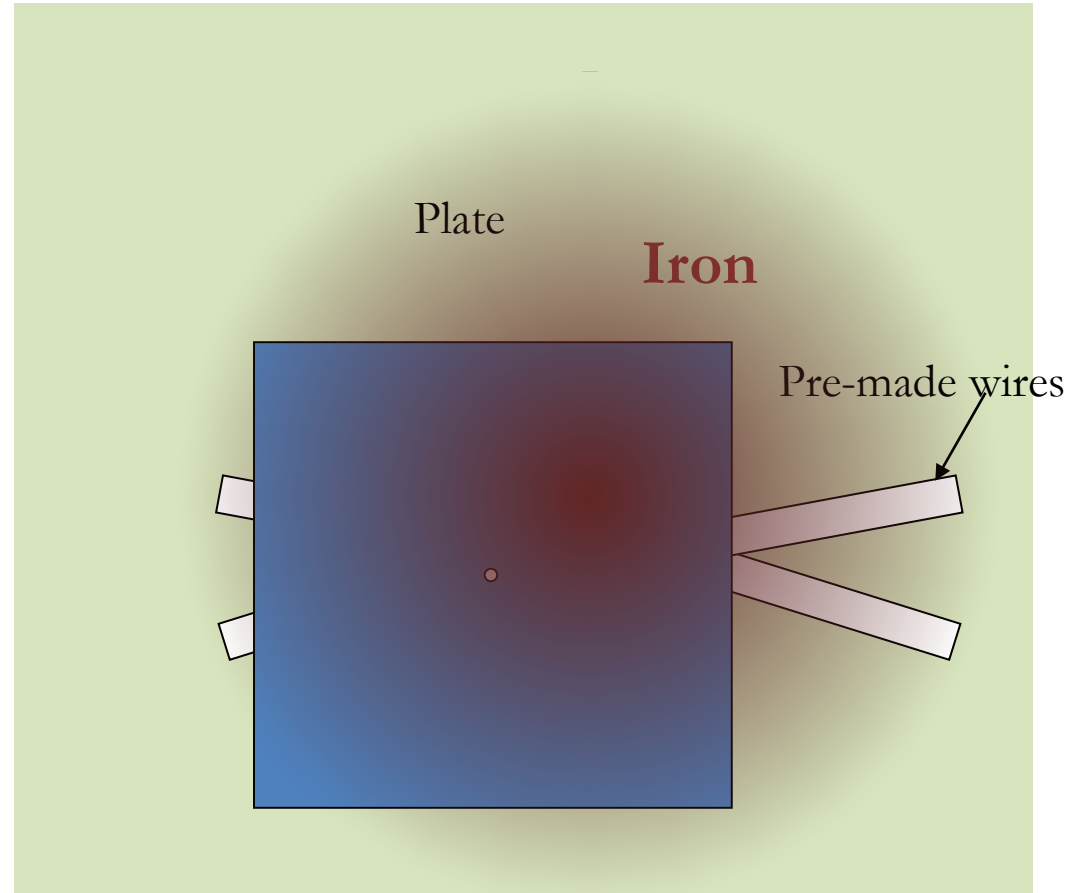
Date :27 Jun 2014



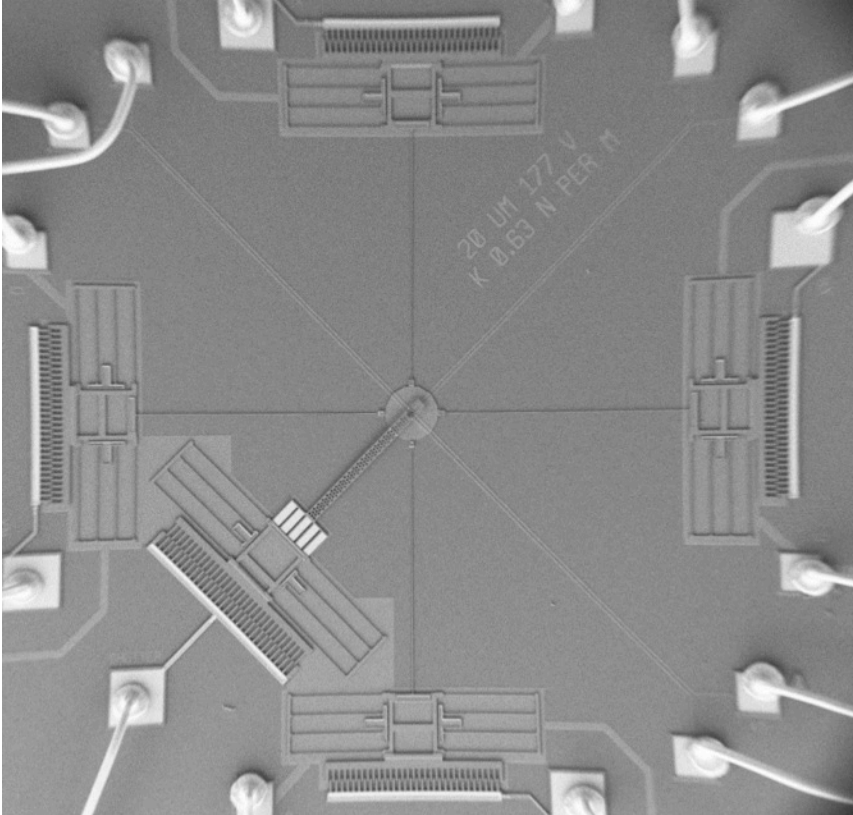
Can “puff off” a wide range of materials
from attograms to nanograms





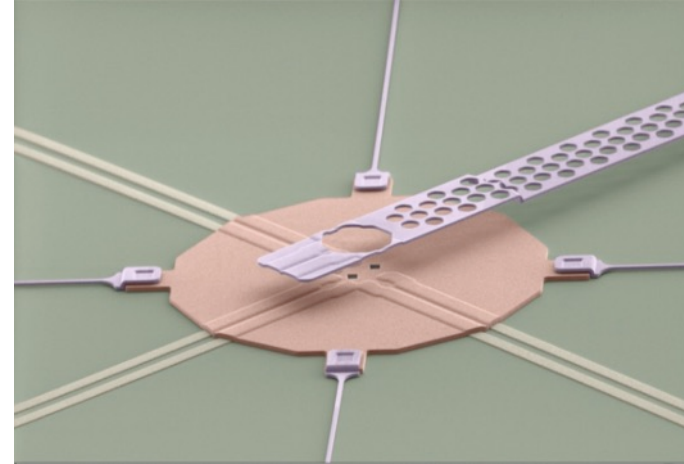


Writers: Placing the Atoms

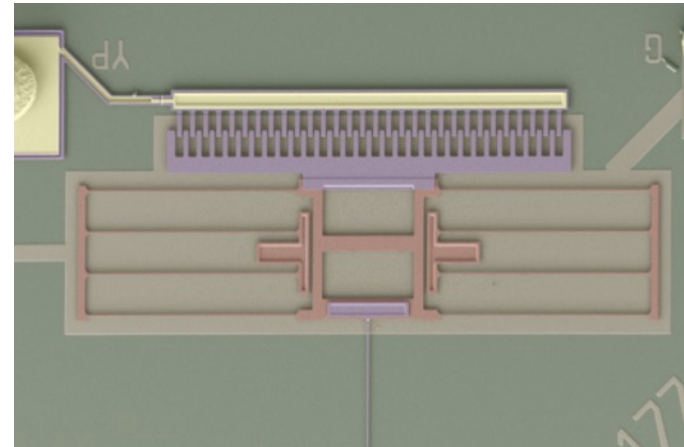


- Aperture shape can be chosen with features well below 50 nm
- Align with Shutter

Shutter, Plate and Apertures

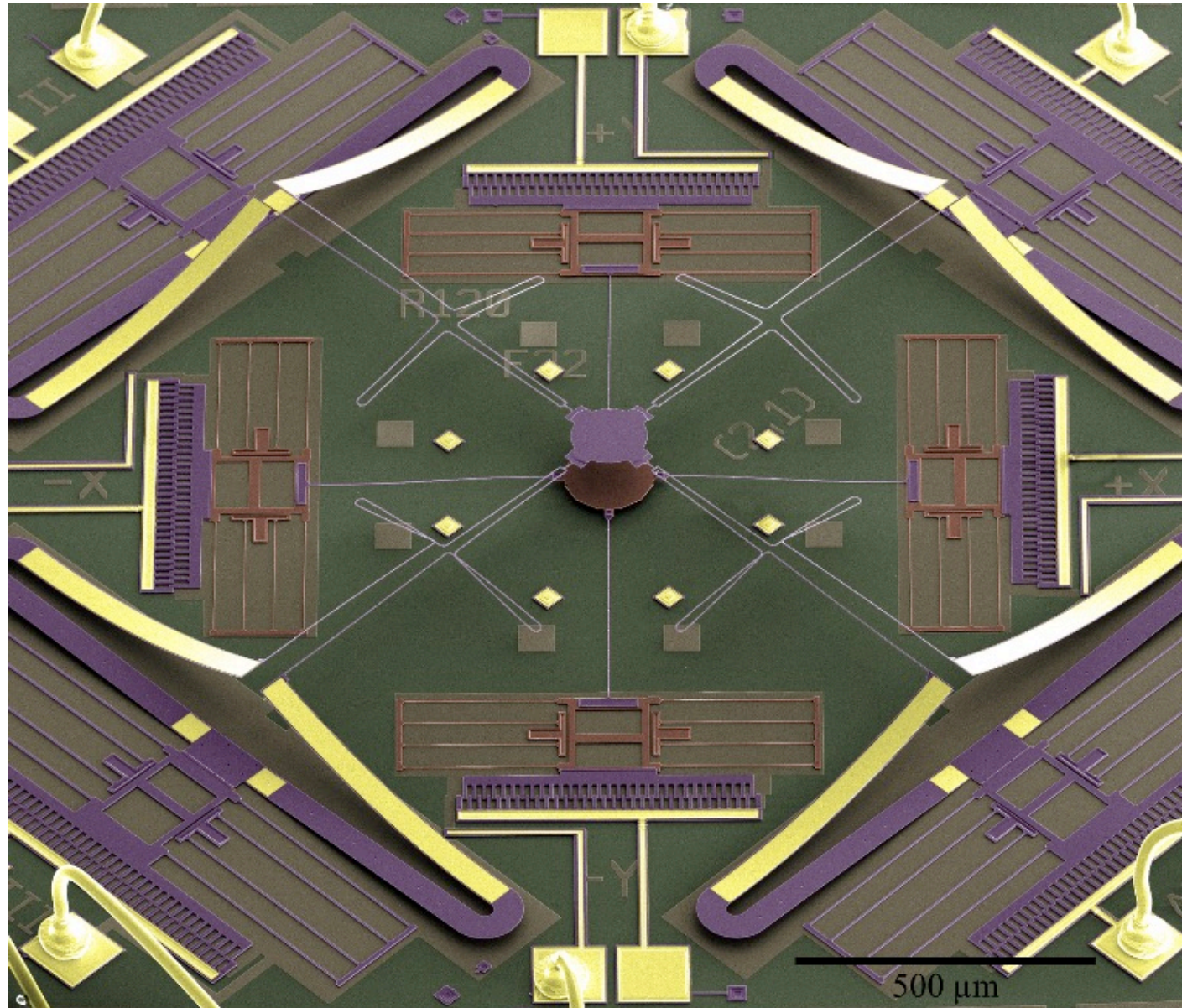


Linear electrostatic motors

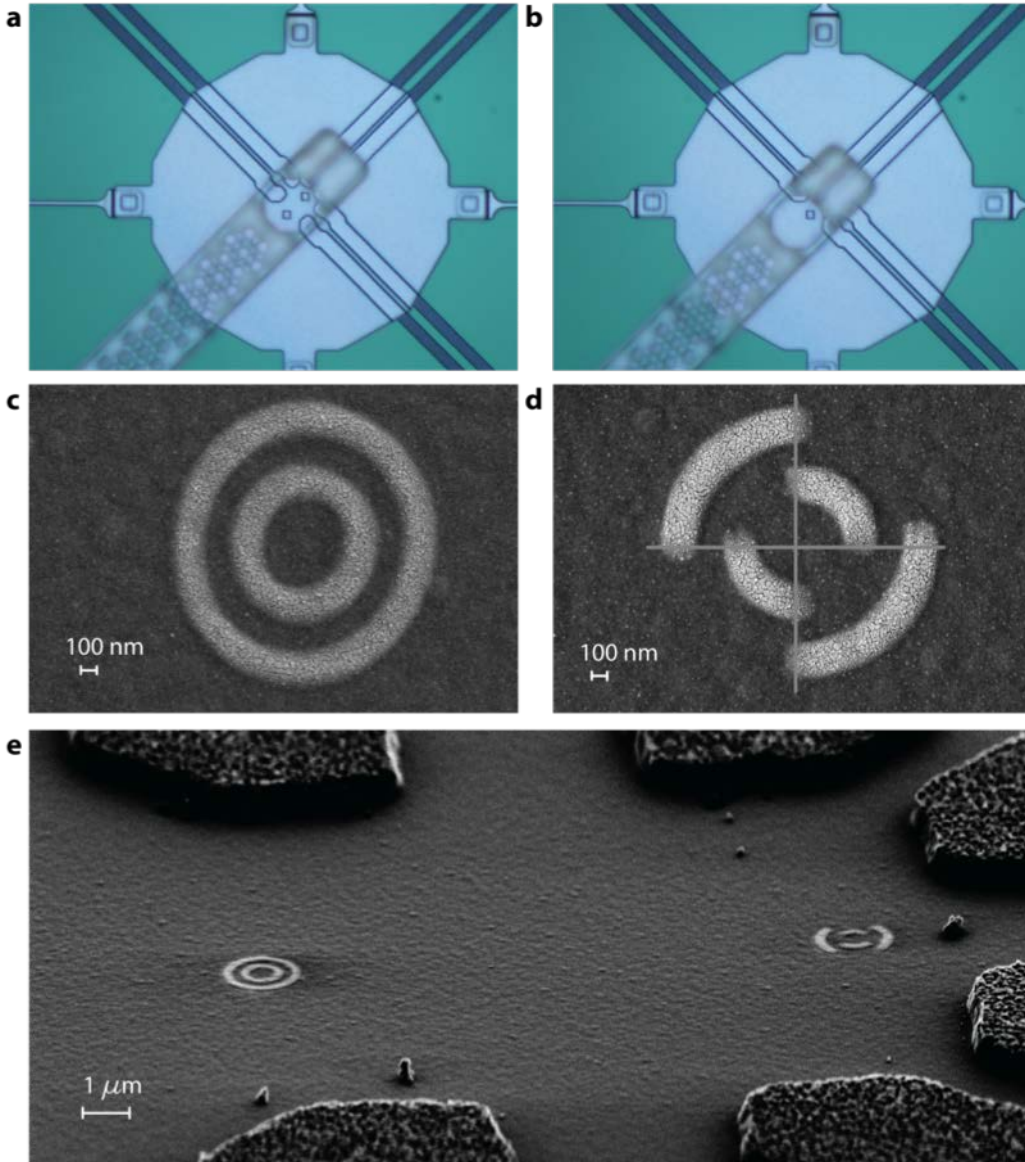


Folded
Flexure
springs

7 DoF MEMS Atomic Writer with 16 Motors and Backside Etch for Thru Wafer Deposition

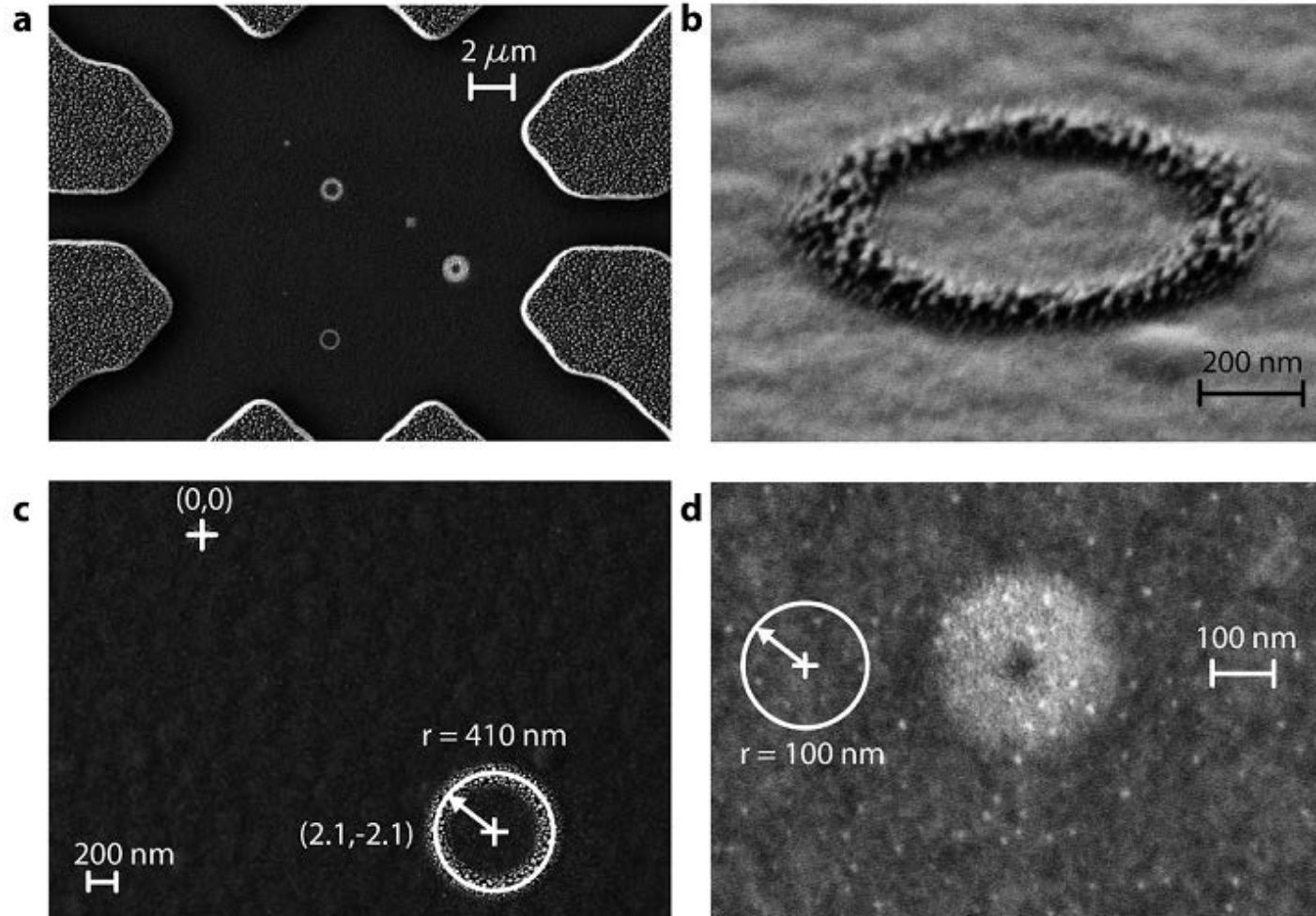


Selective Opening of Apertures

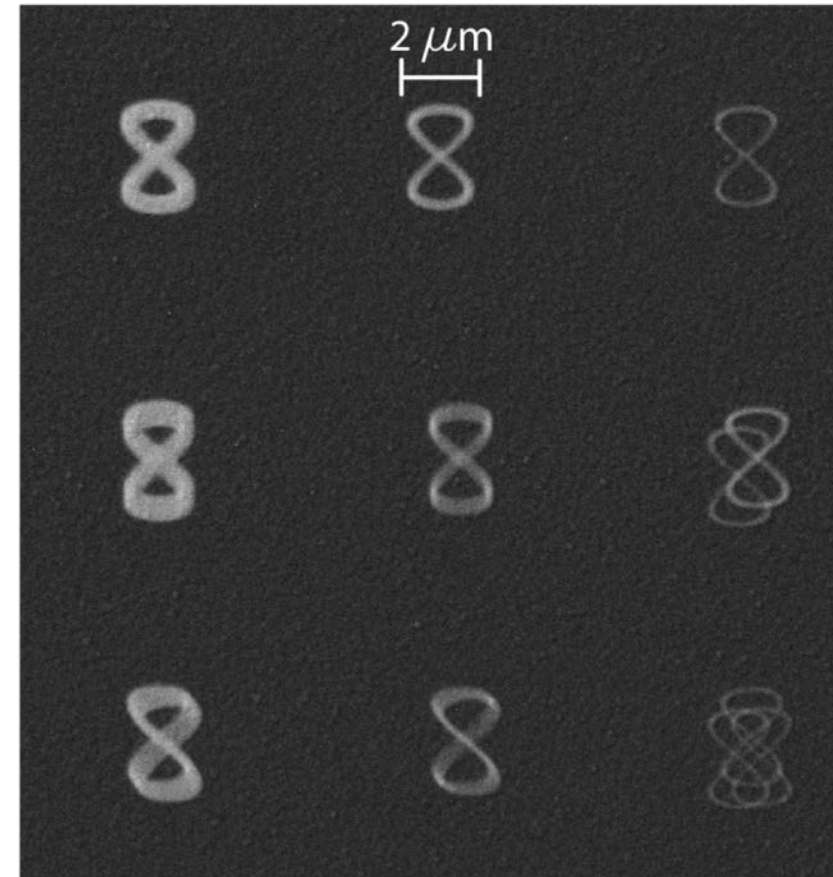
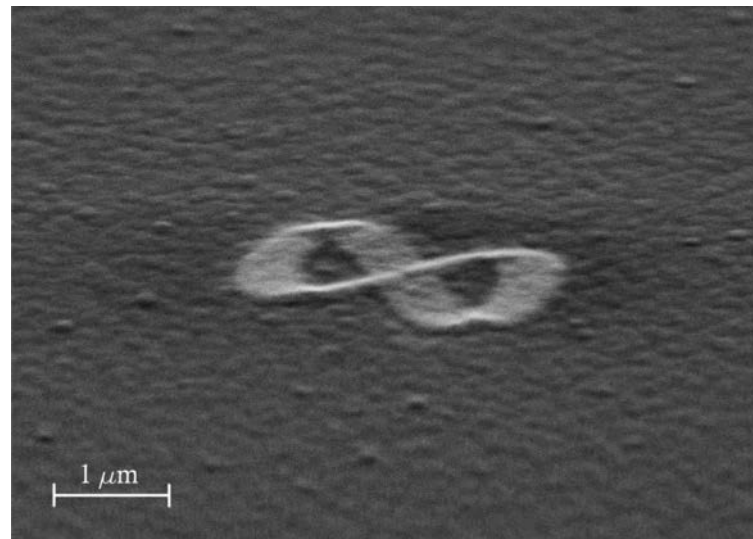
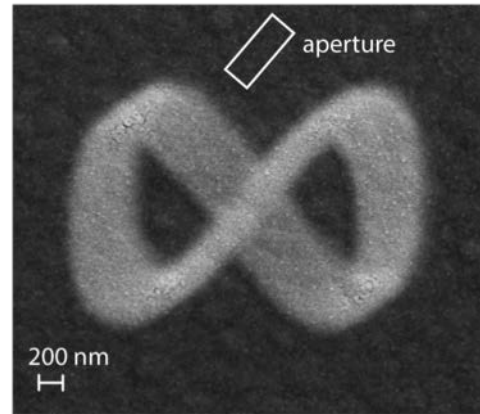


- a. MEMS Shutter open over both sets of apertures
 $V_s = 40$ V
- b. MEMS Shutter closed over one set of apertures and open over the other
 $V_s = 70$ V
- c. Pattern written with continuously open aperture
- d. Pattern written with the aperture and shutter opening and closing during deposition showing the control afforded by the shutter
- e. Larger area image of both patterns

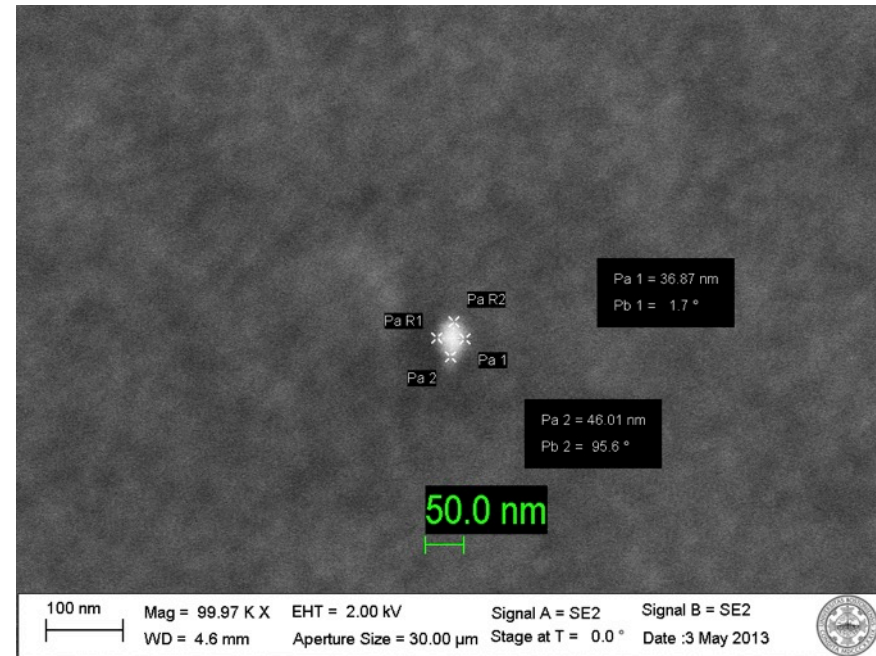
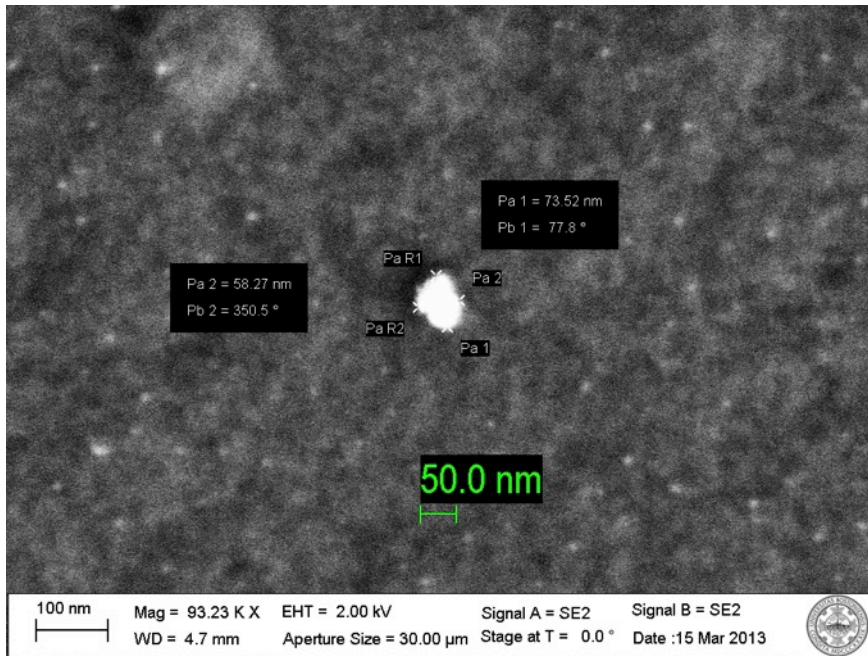
Example Structures: *Rings*



Example Structures: *Lissajous curves*

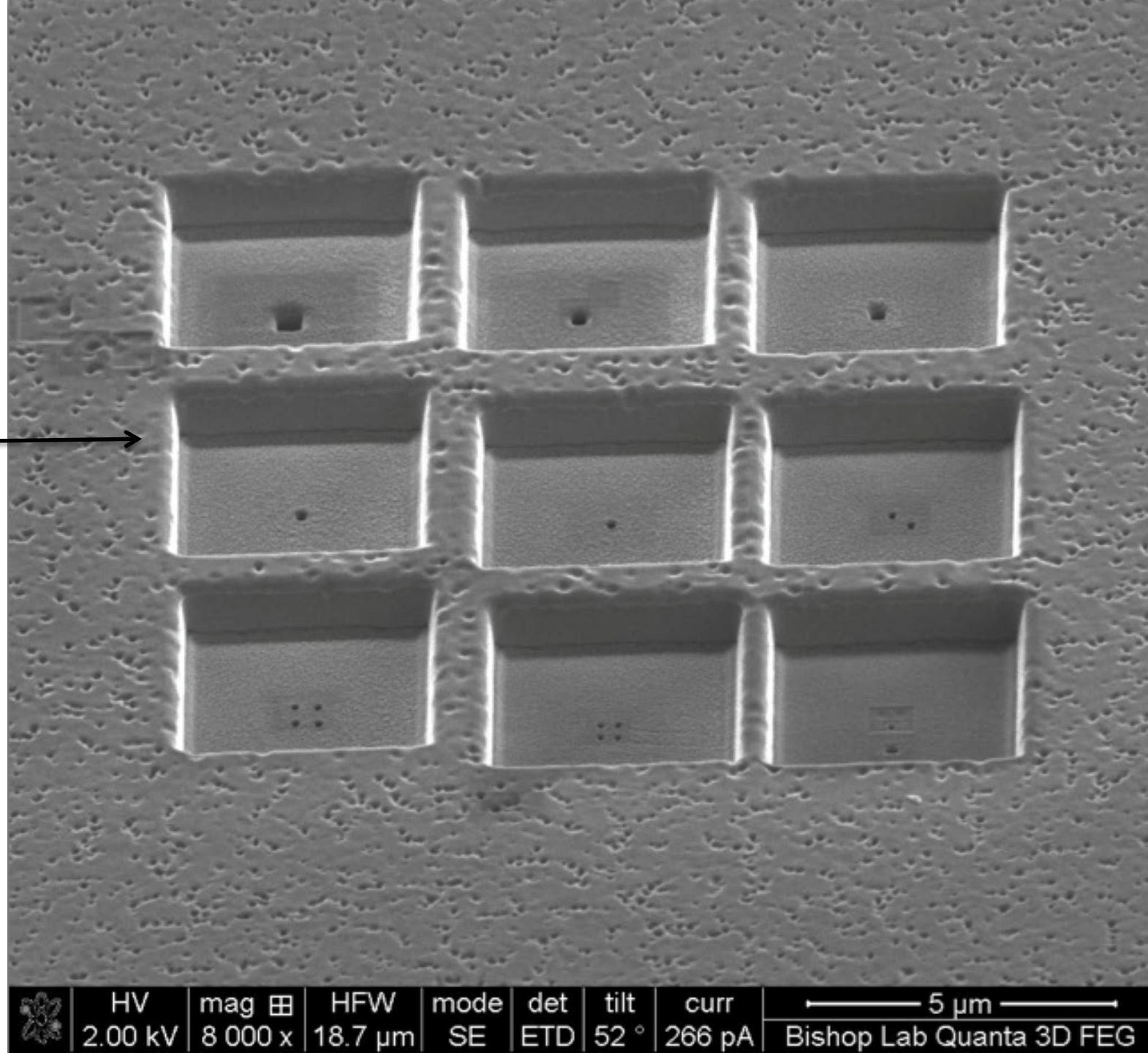


Example Structures: *Chromium nano dots*

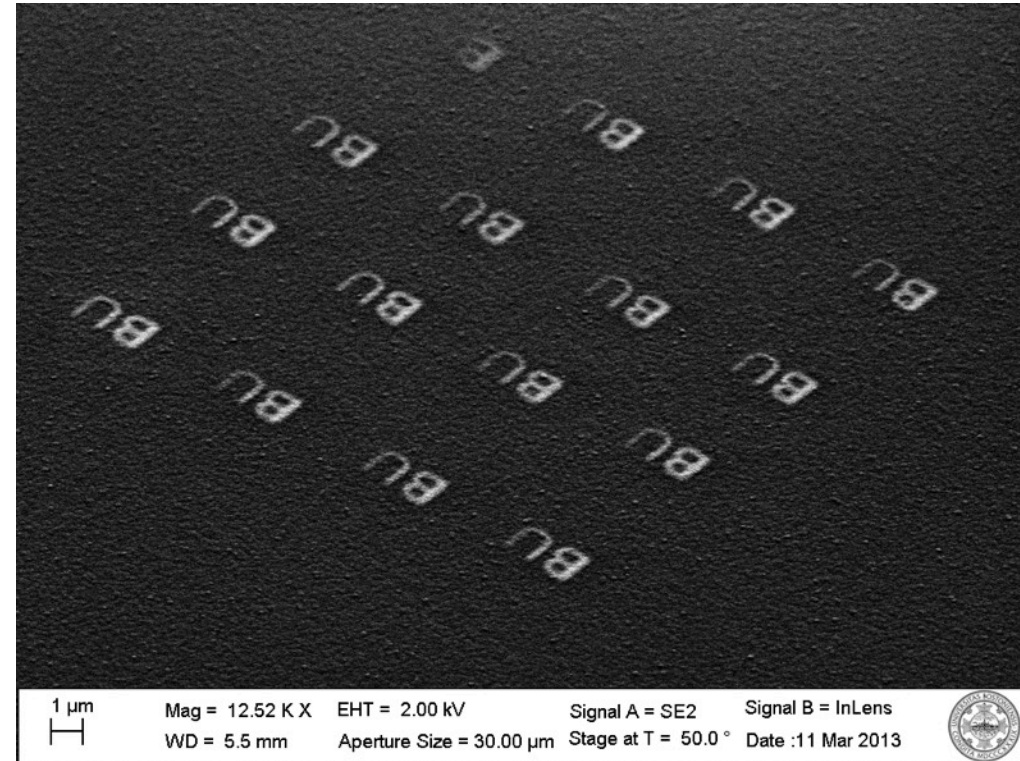
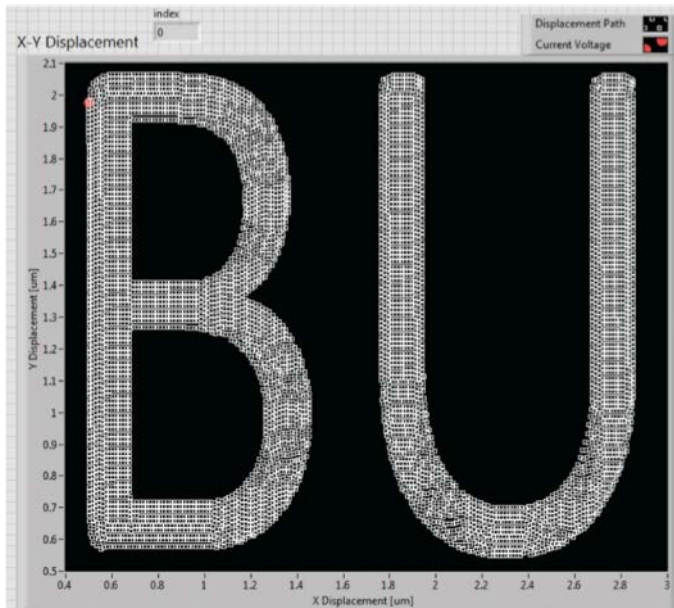
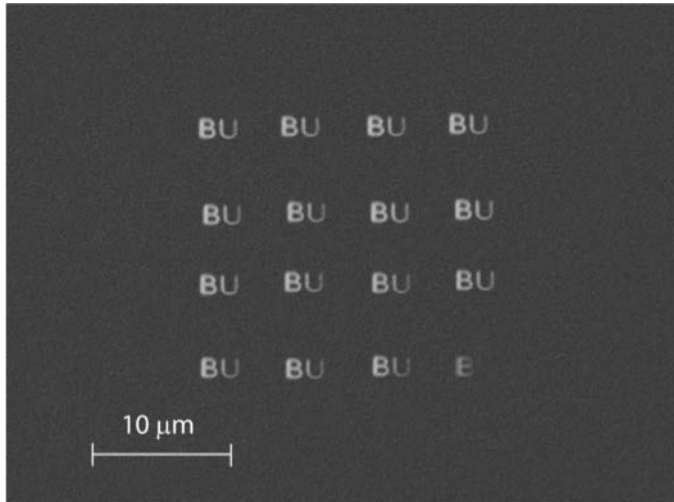


Atoms are placed stochastically within
the aperture opening

Array of
Apertures



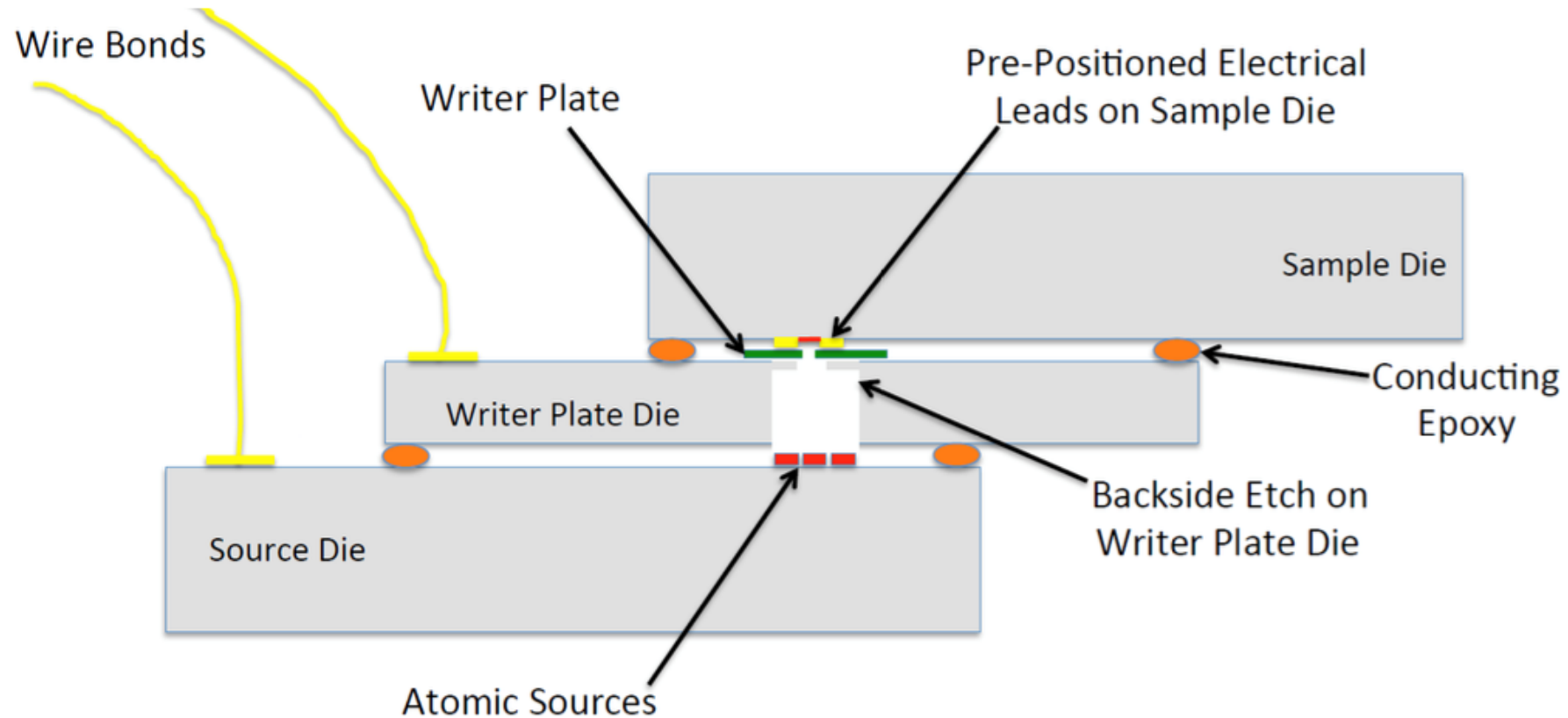
Example Structures: Direct Writing of Arrays



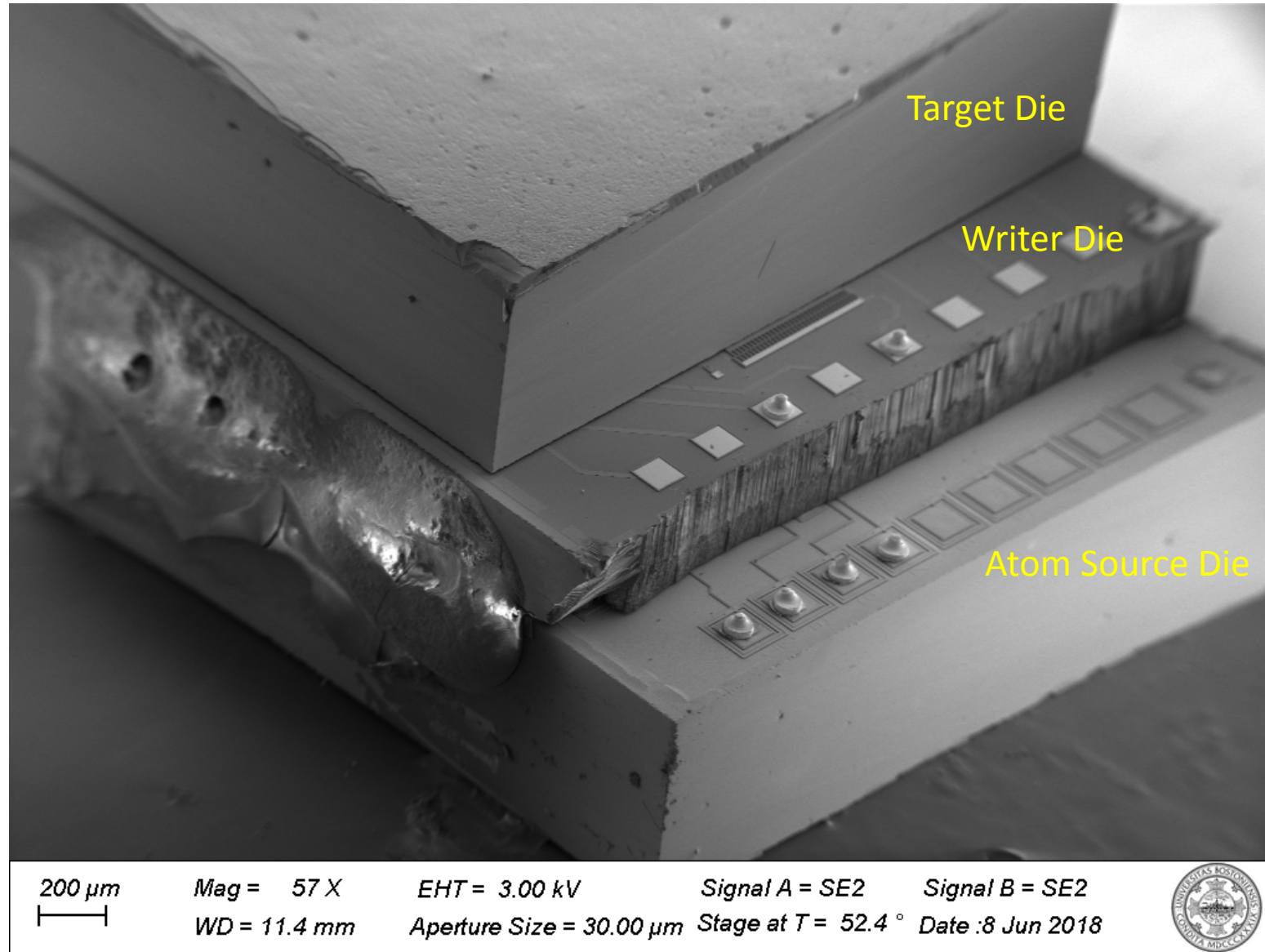
Fully Integrated Fab on a Chip System

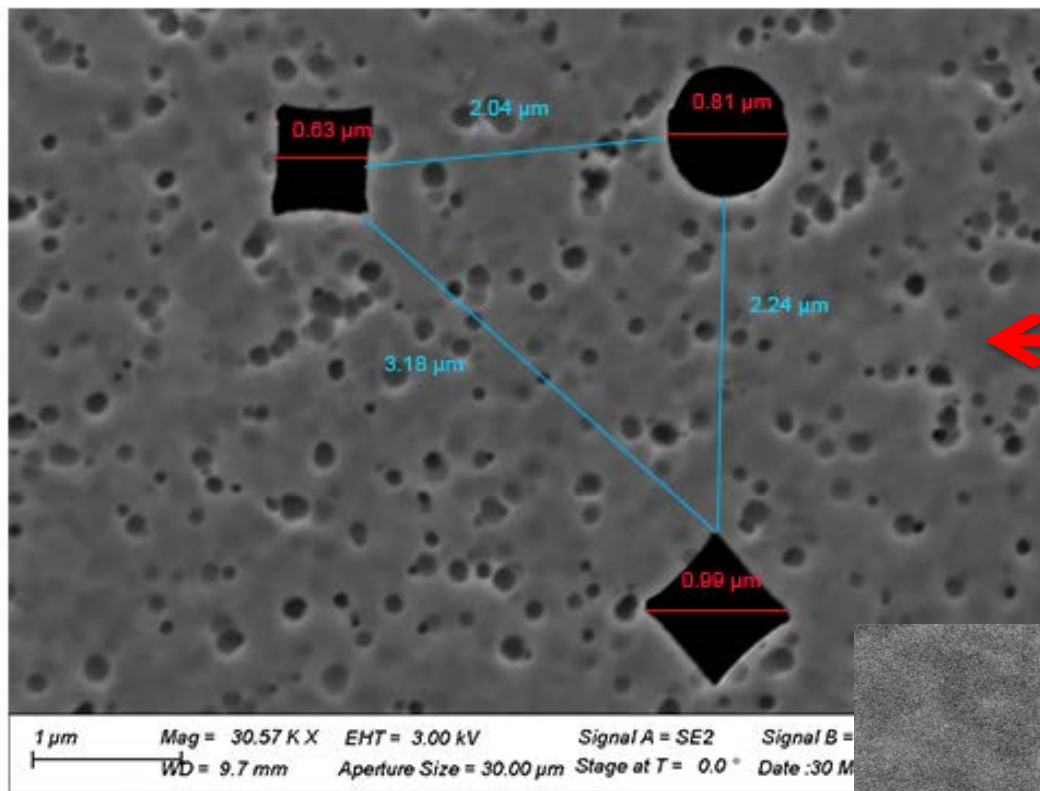
Three Stacked MEMS Devices Create a Fab on a Chip

- Source
 - Writer
 - Sample



Fully Integrated Fab-on-a-Chip





← Apertures on Writing Plate

Pattern, written and then
writing plate moved and
written again →

